

(C) WPI / DERWENT

AN - 1975-11873W [07]

CPY - NOGE-N

DC - M11

FS - CPI

IC - C25F3/02

MC - M11-H03

PA - (NOGE-N) NOGE DENKI KOGYO KK

PN - JP50001351B B 19750117 DW197507 000pp

PR - JP19700099944 19701113

XIC - C25F-003/02

AB - J75001351 The etching soln. contains 10-30 g alkali metal chloride and 0.5-10 cm<sup>3</sup> of 35% HCl per 100 cm<sup>3</sup> water, opt. 80 cm<sup>3</sup> of ≤85% phosphoric acid and ≤60 cm<sup>3</sup> of 95% H<sub>2</sub>SO<sub>4</sub> per 100 cm<sup>3</sup> water may be added to improve the etch. The gold (alloy) is electrolytically etched at high speed, generating little Cl<sub>2</sub>. In an example, etch soln. contained 100 cm<sup>3</sup> water, 10-30 g NaCl, and 0.5-10 cm<sup>3</sup> HCl, a gold plate was etched to good brightness using 4-5V, 0.5-1A dm<sup>-2</sup>, a Mo plate and temp. of 20-40 degrees C.

IW - ELECTROLYTIC ETCH GOLD ALLOY SOLUTION CONTAIN ALKALI METAL CHLORIDE  
HYDROCHLORIC OPTION PHOSPHORIC ACID

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NC - 001

OPD - 1970-11-13

ORD - 1975-01-17

PAW - (NOGE-N) NOGE DENKI KOGYO KK

TI - Electrolytic etching gold (alloy) - using a soln contg alkali metal chloride, hydrochloric and opt phosphoric acids